

TEXT SEARCH.

APPLICATION # 10/671,517

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L40	27	((board or substrate) with (pointed) with (protrusion\$1)).ab,ti,clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 10:35
L41	10	((board or substrate) with (pointed) with (protrusion\$1)).ab,ti,clm.	US-PGPUB; USPAT	OR	OFF	2005/04/04 10:36
L42	17	((board or substrate) with (pointed) with (protrusion\$1)).ab,ti,clm.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 10:37
L43	2	((board or substrate) with (pointed) with (conductive adj bump\$1)).ab,ti,clm.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 10:40
L44	0	((board or substrate) with (pointed) with (conductive adj bump\$1)).ab,ti,clm.	US-PGPUB; USPAT	OR	OFF	2005/04/04 10:41
L45	439	((board or substrate) with (conductive adj bump\$1)).ab,ti,clm.	US-PGPUB; USPAT	OR	OFF	2005/04/04 10:43
L46	5	(board or substrate) with (conductive adj bump\$1) with (penetrate or penetration)	US-PGPUB; USPAT	OR	OFF	2005/04/04 10:47
L47	10	(board or substrate) with (conductive adj bump\$1) with (penetrate or penetration)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 10:55
L48	4	(conductive adj bump\$1) with (sharp adj tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 11:03
L49	14	(thermoplastic adj film) with (liquid adj crystal adj polymer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 11:42
L50	113	(thermosetting adj resin) with (adhesive adj properties)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 11:44
L51	46	50 and thermoplastic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 11:43

L52	46	((thermosetting adj resin) with (adhesive adj properties)) and (thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 12:03
L58	13365	(synthetic adj resin) with (thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 12:06
S26	1194	(insulating adj layer or insulation adj layer or resin adj layer or adhesive adj layer) with (thermosetting) with (thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/02 17:10
S27	41	S26 and (three adj layer adj structure)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/02 17:11
S28	520	(insulating adj film or insulation adj film or resin adj film or adhesive adj film) with (thermosetting) with (thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/02 17:10
S29	14	S28 and (three adj layer adj structure)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/02 17:17
S30	1599	S26 or S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/02 17:24
S31	833	S30 and (board or substrate or circuit adj structure)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/02 17:18

S32	362	S30 and (compound adj layer or composite)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/02 17:39
S47	520	(insulating adj film or insulation adj film or resin adj film or adhesive adj film) with (thermosetting) with (thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/03 17:26
S48	38542	(thermosetting) with (thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/03 17:27
S49	631	(thermosetting adj adhesive) with (thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/03 17:27
S50	13	(thermosetting adj adhesive) with (thermoplastic adj film)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/03 17:30